

# BTA25-600CW3G, BTA25-800CW3G





#### **Description**

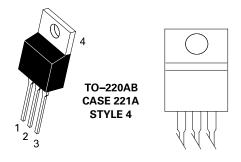
Designed primarily for half-wave ac control applications, such as motor controls, heating controls and power supply crowbar circuits.

#### **Features**

- Blocking Voltage to 800 V
- On-State Current Rating of 25 A RMS at 25°C
- Uniform Gate Trigger Currents in Three Quadrants
- High Immunity to dV/ dt – 500 V/μs minimum at 125°C
- Minimizes Snubber Networks for Protection

- Industry Standard TO-220AB Package
- High Commutating dl/ dt – 14 A/ms minimum at 125°C
- Internally Isolated (2500 V<sub>RMS</sub>)
- These are Pb–Free Devices and are RoHS Compliant

#### **Pin Out**



#### **Functional Diagram**



### **Additional Information**







Samples

# **Thyristors** Surface Mount - 800V > BTA25-600CW3G, BTA25-800CW3G

#### Maximum Ratings (T = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off-State Voltage (Note 1) BTA25–600CW (Gate Open, Sine Wave 50 to 60 Hz, $T_{\rm J}$ = -40° to 125°C) BTA25–800CW	DRM'	600 800	V
On-State RMS Current (Full Cycle Sine Wave, 60 Hz, T <sub>C</sub> = 95°C)	I <sub>T (RMS)</sub>	25	А
Peak Non-Repetitive Surge Current (One Full Cycle Sine Wave, 60 Hz, $T_c = 25^{\circ}\text{C}$ )	I <sub>TSM</sub>	250	А
Circuit Fusing Consideration (t = 8.3 ms)	l²t	260	A²sec
Non-Repetitive Surge Peak Off-State Voltage (T <sub>J</sub> = 25°C, t = 8.3 ms)	$V_{DSM}/V_{RSM}$	V <sub>DSM</sub> / V <sub>RSM</sub> +100	V
Peak Gate Current (T <sub>J</sub> = 110°C, t ≤ 20µs)	I <sub>GM</sub>	4.0	W
Peak Gate Power (Pulse Width $\leq$ 20 $\mu$ s, T $_{\rm C}$ = 80°C)	P <sub>G(AV)</sub>	20	W
Average Gate Power (T <sub>J</sub> = 110°C)	P <sub>G(AV)</sub>	1.0	W
Operating Junction Temperature Range	T <sub>J</sub>	-40 to +125	°C
Storage Temperature Range	T <sub>stg</sub>	-40 to +125	°C
RMS Isolation Voltage (t = 300 ms, R.H. $\leq$ 30%, $T_A$ = 25°C)	V <sub>iso</sub>	2500	V

#### **Thermal Characteristics**

Rating		Symbol	Value	Unit
Thermal Resistance,	Junction-to-Case (AC) Junction-to-Ambient	R <sub>ejc</sub> R <sub>eja</sub>	2.13 60	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds		$T_L$	260	°C

#### **Electrical Characteristics - OFF** $(T_1 = 25^{\circ}\text{C unless otherwise noted}; \text{Electricals apply in both directions})$

Characteristic		Symbol	Min	Тур	Max	Unit
Peak Repetitive Blocking Current	T, = 25°C	I <sub>DRM</sub> ,	-	-	0.005	m ^
$(V_D = V_{DRM} = V_{RRM}; Gate Open)$	T <sub>J</sub> = 110°C	I	-	-	2.0	mA

#### Electrical Characteristics - ON (T, = 25°C unless otherwise noted; Electricals apply in both directions)

Characteristic		Symbol	Min	Тур	Max	Unit
Forward On-State Voltage (Note 2) ( $I_{TM} = \pm 22.5 \text{ A Peak}$ )		V <sub>TM</sub>	-	-	1.55	V
	MT2(+), G(+)		2.0	_	10	
Gate Trigger Current (Continuous dc) ( $V_D = 12 \text{ V}, R_L = 30 \Omega$ )	MT2(+), G(-)	l <sub>gt</sub>	2.0	_	10	mA
	MT2(-), G(-)		2.0	_	10	
Holding Current ( $V_D = 12 \text{ V}$ , Gate Open, Initiating Current = ±500 mA)		IH	-	_	20	mA
	MT2(+), G(+)	IL	-	_	25	mA
Latching Current ( $V_D = 12 \text{ V}, I_G = 12 \text{ mA}$ )	MT2(+), G(-)		-	-	30	
	MT2(-), G(-)		-	-	25	
	MT2(+), G(+)		0.5	-	1.3	
Gate Trigger Voltage ( $V_D = 12 \text{ V}, R_L = 30 \Omega$ )	MT2(+), G(-)	V <sub>GT</sub>	0.5	_	1.3	V
	MT2(-), G(-)		0.5	-	1.3	
	MT2(+), G(+)		0.2	_	_	
Gate Non-Trigger Voltage (T <sub>J</sub> = 110°C)	MT2(+), G(-)	V <sub>GD</sub>	0.2	_	_	V
	MT2(-), G(-)		0.2	-	-	

<sup>2.</sup> Indicates Pulse Test: Pulse Width  $\leq$  2.0 ms, Duty Cycle  $\leq$  2%.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. V<sub>DRM</sub> and V<sub>RRM</sub> for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

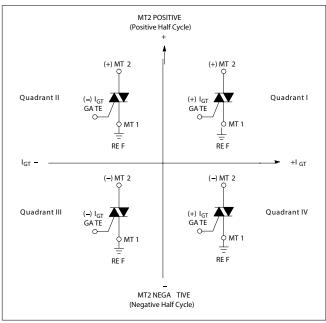


#### **Dynamic Characteristics** Characteristic **Symbol** Min Max Unit Тур Rate of Change of Commutating Current, See Figure 10. (dl/dt)c 2.0 A/ms (Gate Open, T<sub>J</sub> = 110°C, No Snubber) Critical Rate of Rise of On-State Current dl/dt 50 A/µs $(T_J = 110^{\circ}\text{C}, f = 120 \text{ Hz}, I_G = 20 \text{ mA}, \text{ tr} \le 100 \text{ ns})$ Critical Rate of Rise of Off-State Voltage dV/dt 250 V/µs $(V_D = 0.66 \text{ x } V_{DRM}, \text{ Exponential Waveform, Gate Open, } T_J = 110^{\circ}\text{C})$

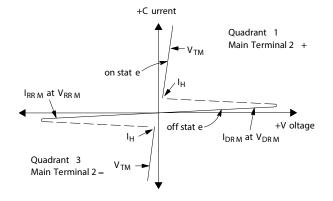
### **Voltage Current Characteristic of SCR**

Symbol	Parameter
V <sub>DRM</sub>	Peak Repetitive Forward Off State Voltage
I <sub>DRM</sub>	Peak Forward Blocking Current
V <sub>RRM</sub>	Peak Repetitive Reverse Off State Voltage
IRRM	Peak Reverse Blocking Current
$V_{TM}$	Maximum On State Voltage
I <sub>H</sub>	Holding Current

#### **Quadrant Definitions for a Triac**



All polarities are referenced to MT1.
With in–phase signals (using standard AC lines) quadrants I and III are used





**Figure 1. RMS Current Derating** 

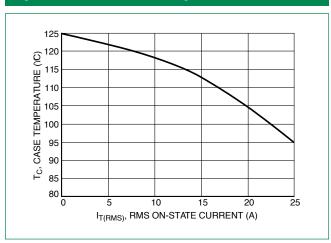


Figure 2. On-State Power Dissipation

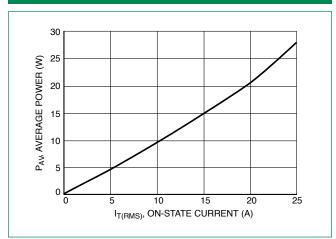


Figure 3. On-State Characteristics

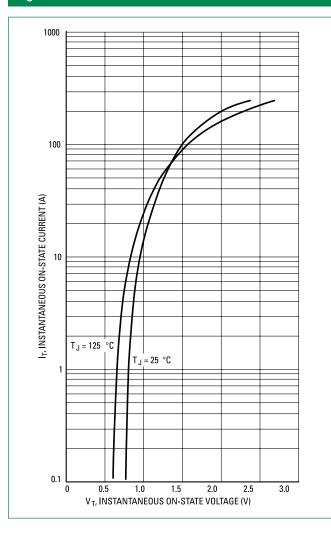


Figure 4. Thermal Response

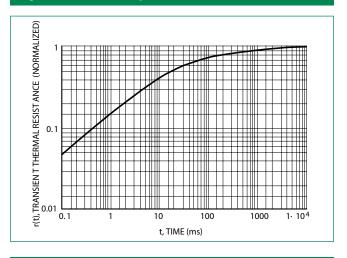
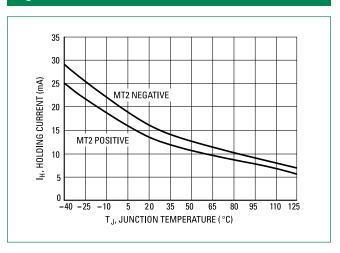


Figure 5. Hold Current Variation







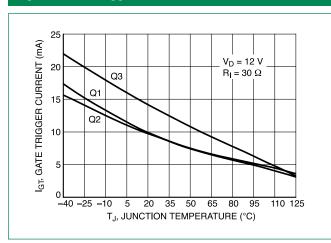


Figure 7. Gate Trigger Voltage Variation

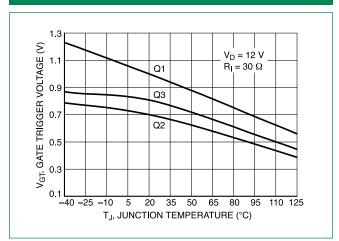


Figure 8. Critical Rate of Rise of Off-State Voltage (Exponential Waveform)

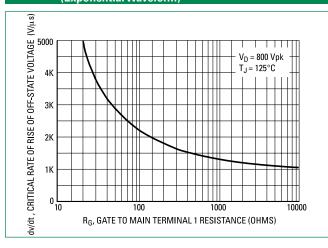


Figure 9. Latching Current Variation

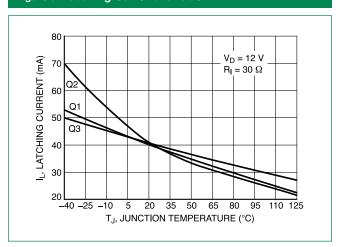
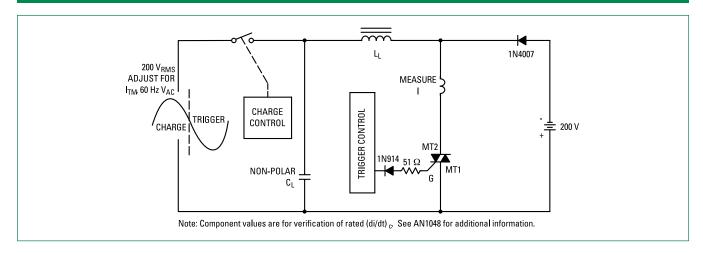
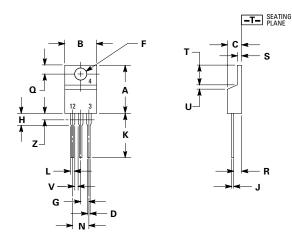


Figure 10. Simplified Test Circuit to Measure the Critical Rate of Rise of Commutating Current (di/dt)

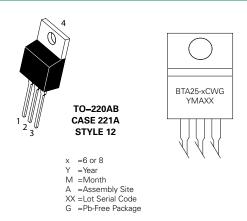




#### **Dimensions**



## **Part Marking System**



Di	Inches		Millin	eters	
Dim	Min	Max	Min	Max	
Α	0.590	0.620	14.99	15.75	
В	0.380	0.420	9.65	10.67	
С	0.178	0.188	4.52	4.78	
D	0.025	0.035	0.64	0.89	
F	0.142	0.147	3.61	3.73	
G	0.095	0.105	2.41	2.67	
Н	0.110	0.130	2.79	3.30	
J	0.018	0.024	0.46	0.61	
K	0.540	0.575	13.72	14.61	
L	0.060	0.075	1.52	1.91	
N	0.195	0.205	4.95	5.21	
Q	0.105	0.115	2.67	2.92	
R	0.085	0.095	2.16	2.41	
s	0.045	0.060	1.14	1.52	
Т	0.235	0.255	5.97	6.47	
U	0.000	0.050	0.00	1.27	
V	0.045		1.15	_	
Z		0.080		2.04	

Pin Assignment			
1	Main Terminal 1		
2	Main Terminal 2		
3	Gate		
4	No Connection		

Ordering	Information

Device	Package	Shipping
BTA25-600SW3G	TO-220AB (Pb-Free)	500 Units / Rail
BTA25-800SW3G	TO-220AB (Pb-Free)	500 Units / Rail

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
- DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.